IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Donald Malcolm MacIntyre

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Group Art Unit: 2814

Examiner: D. Wille

RESPONSE TO FINAL REJECTION MAILED JULY 3, 2001

121 Spear Street, Suite 290
San Francisco, CA 94105
(415) 512-1312

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope, addressed to: Commissioner for Patents, Washington, DC 20231 on November 29, 2001.

STALLMAN & POLLOCK LLP

Dated: 11/29/2001 By: Georgia K. Stith

Georgia K. Stith

Commissioner for Patents
Washington, D.C. 20231

Sir:

Please amend the above-identified application as follows:

IN THE CLAIMS

Please cancel claims 39-48 and add the following new claims:

--49. (New) A semiconductor integrated circuit wafer scale structure comprising:

a semiconductor wafer substrate that includes a plurality of semiconductor integrated circuit die formed on an upper surface of the wafer substrate, each semiconductor integrated circuit die formed on the wafer substrate including a plurality of conductive die bond pads formed on an upper surface of said integrated circuit die;

a unitary, substantially planar glass sheet having substantially the same size as the wafer substrate and having a plurality of prefabricated holes formed therethrough from an upper surface of the glass sheet to a lower surface of the glass sheet, each prefabricated